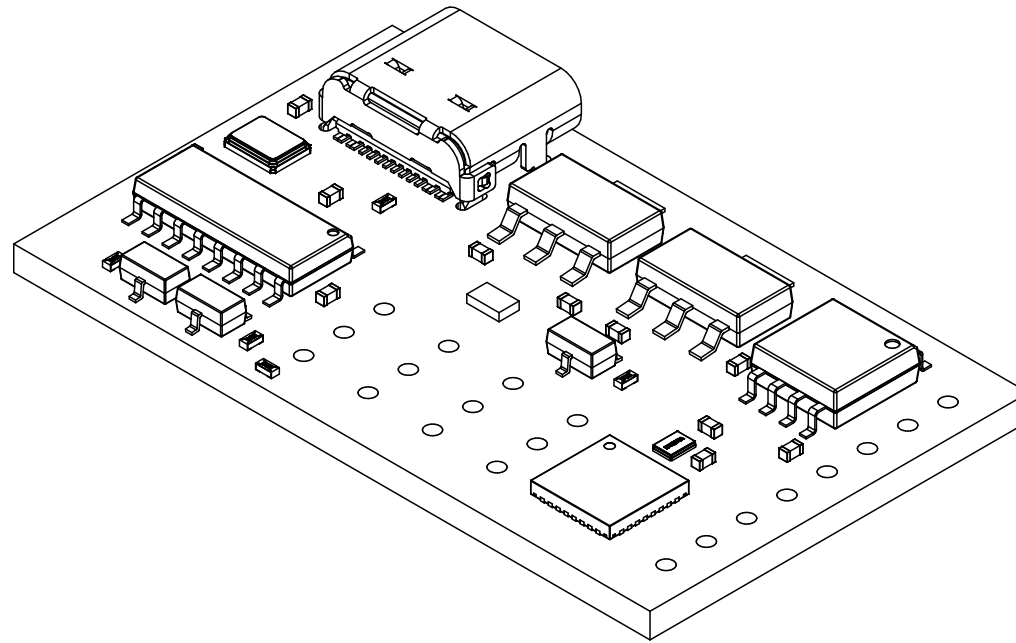
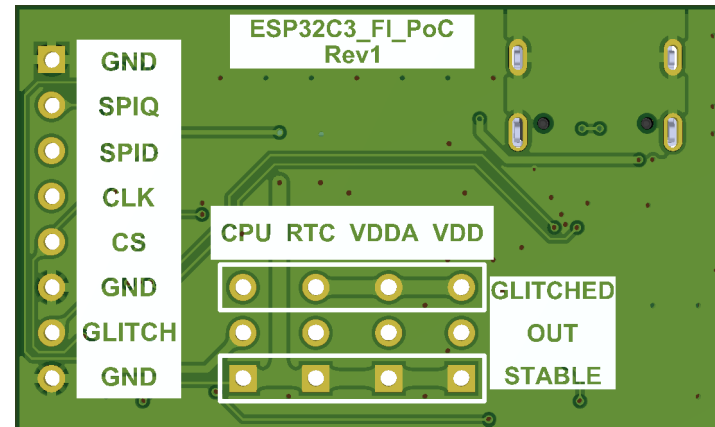
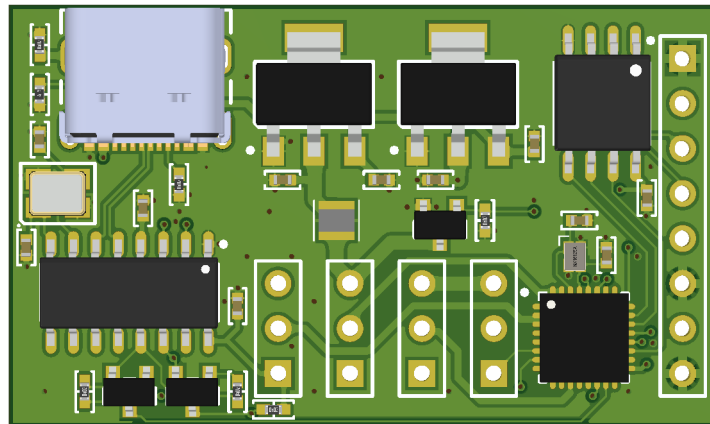
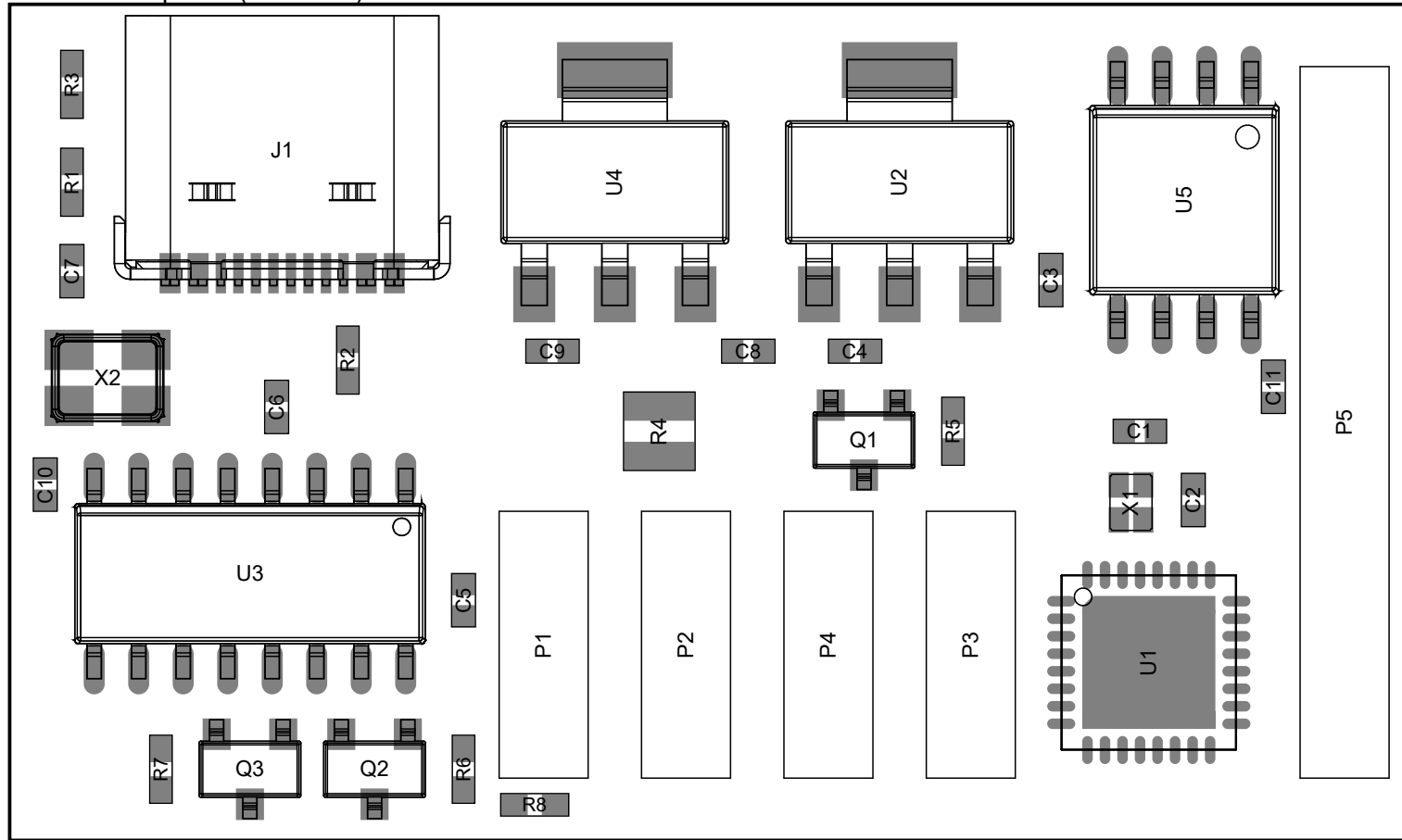


ESP32C3_FI_PoC (1.0)



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|------------------|----------------|
| Project | ESP32C3_FI_PoC |
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View from Top side (Scale 5:1)



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Bill Of Materials

| Line # | Designator | Quantity | Footprint | Tolerance | Value | Manufacturer | Material | Part Name |
|--------|---------------------|----------|--------------------|-----------------|-------|--------------------------------------|----------------|----------------------------|
| 1 | C1, C2, C5, C6 | 4 | C0402 | [NoParam], ±10% | 10nF | [NoParam], Samsung Electro-Mechanics | [NoParam], X7R | C15195 |
| 2 | C3, C4, C8, C9, C11 | 5 | C0402 | ±10% | 100nF | Samsung Electro-Mechanics | X7R | C1525 |
| 3 | C7, C10 | 2 | C0402 | ±5% | 33pF | Guangdong Fenghua Advanced Tech | C0G | C1562 |
| 4 | J1 | 1 | USB4105-GF-A | | | GCT | | USB4105-GF-A |
| 5 | P1, P2, P3, P4 | 4 | HDR1X3 | | | | | |
| 6 | P5 | 1 | HDR1X8 | | | | | |
| 7 | Q1 | 1 | SOT-23-3 | | | | | IRLML2502 |
| 8 | Q2, Q3 | 2 | SOT-23-3-BIPOLAR | | | LRC | | L8050QLT1G |
| 9 | R1, R2 | 2 | R0402 | ±1% | 5.1KΩ | Uniroyal Elec | | C25905 |
| 10 | R4 | 1 | ERJB3 | 1% | 7.5 | | | ERJ-B3BF7R5V |
| 11 | R5, R6, R7, R8 | 4 | R0402 | ±1% | 10KΩ | Uniroyal Elec | | C25744 |
| 12 | U1 | 1 | QFN-32 | | | Espressif | | ESP32-C3 |
| 13 | U2, U4 | 2 | SOT-223 | | | | | AMS1117-3.3 |
| 14 | U3 | 1 | SOP-16 | | | Jiangsu Qin Heng | | CH340G |
| 15 | U5 | 1 | SOIC127P790X216-8N | | | Winbond | | W25Q32JVSSIQS |
| 16 | X1 | 1 | CRYSTAL_1_6x1_2 | | | | | ABM12W-40.0000MHZ-7-B1U-T3 |
| 17 | X2 | 1 | TSX-3225 | | | Yangxing Tech | | X322512MSB4SI |

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

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Layer Stack Legend

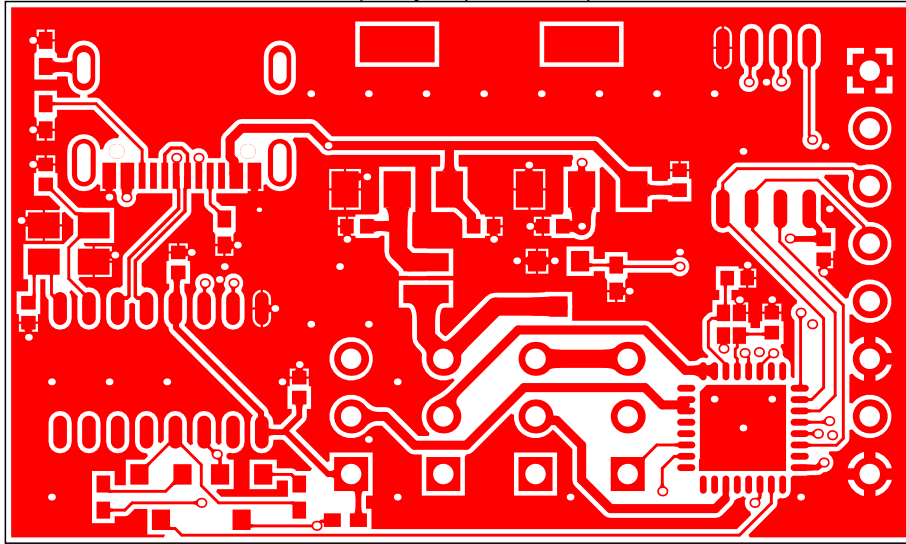
| Material | Layer | Thickness | Dielectric Material | Type | Gerber |
|------------------|---------------------|----------------|---------------------|----------------|------------|
| | Top Overlay | | | Legend | GTO |
| Surface Material | Top Solder | 0.020mm | Solder Resist | Solder Mask | GTS |
| Copper | Top Layer | 0.035mm | | Signal | GTL |
| Prepreg | | 0.099mm | PP-006 | Dielectric | |
| CF-004 | Layer 1 | 0.015mm | | Internal Plane | GP1 |
| | | 1.265mm | FR-4 | Dielectric | |
| CF-004 | Layer 2 | 0.015mm | | Internal Plane | GP2 |
| Prepreg | | 0.099mm | PP-006 | Dielectric | |
| Copper | Bottom Layer | 0.035mm | | Signal | GBL |
| Surface Material | Bottom Solder | 0.020mm | Solder Resist | Solder Mask | GBS |
| | Bottom Overlay | | | Legend | GBO |

Total thickness: 1.605mm

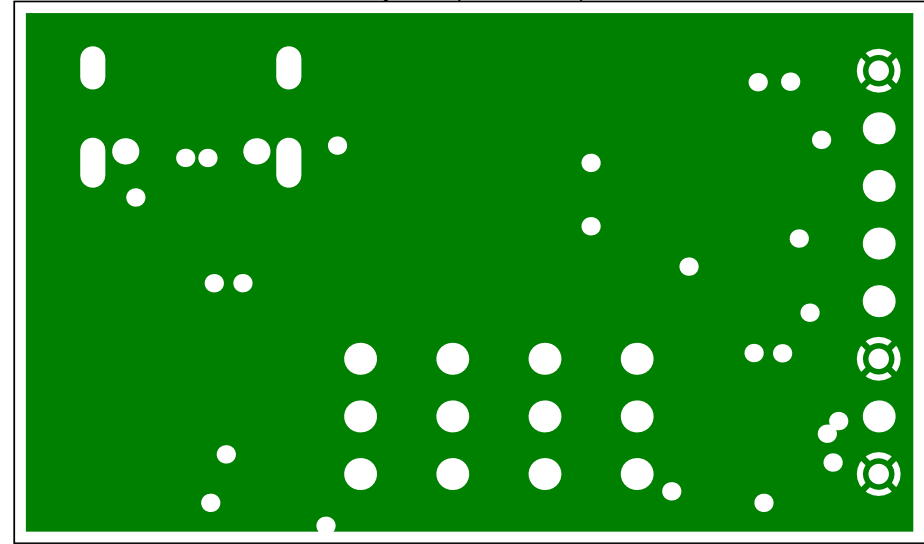
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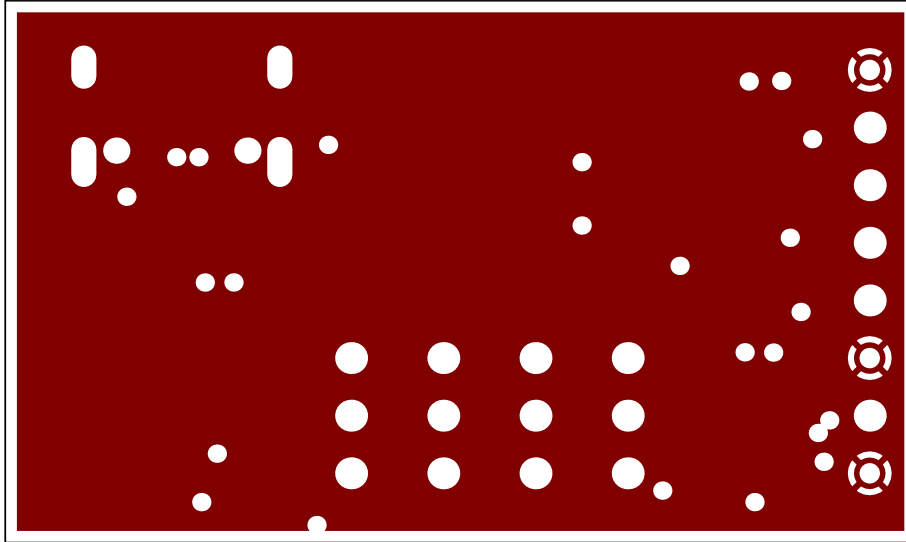
Top Layer (Scale 3:1)



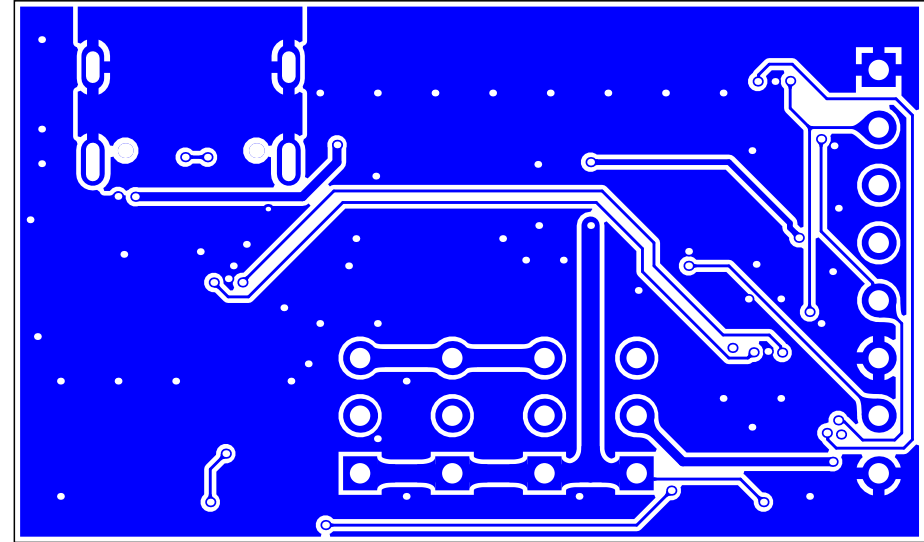
Layer 1 (Scale 3:1)




Layer 2 (Scale 3:1)




Bottom Layer (Scale 3:1)



| | |
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